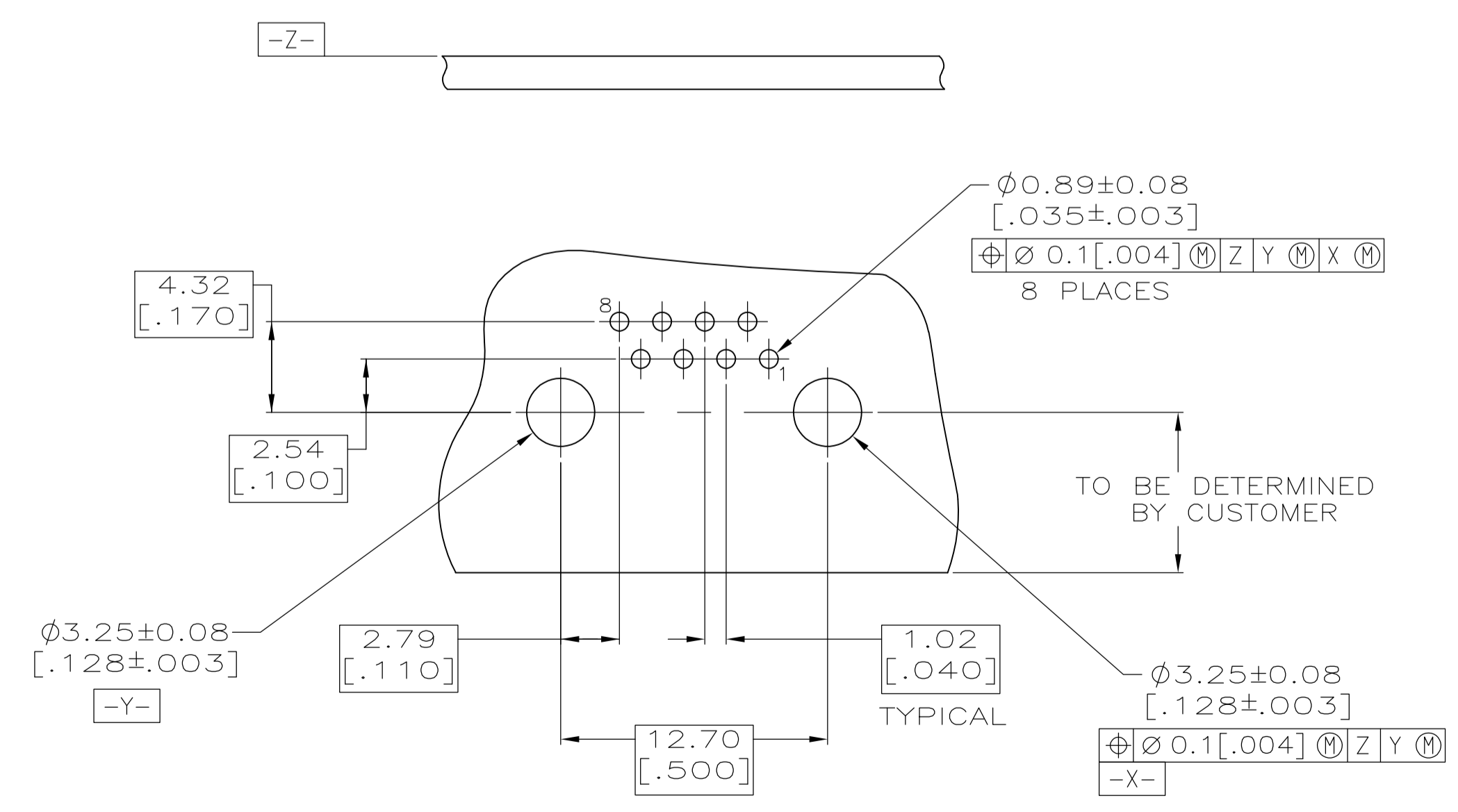


- △ MATERIAL:
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0; IR REFLOW SOLDERING PROCESS COMPATIBLE.
 TERMINALS - .36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK (SEE P/N TABLE) IN SOLDER AREA. 1.27µm[.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm[.000050] MINIMUM THICK NICKEL.
2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
- △ SUGGESTED CLEARANCE BETWEEN BOTTOM OF CONNECTOR AND BOTTOM PANEL OPENING.
- △ PACKAGED 35 PIECES PER TUBE, SEE DETAIL "A".
- △ 80 PIECES/TRAY, 10 TRAYS/BOX.
- △ MANUFACTURING DATE CODE:
 INK STAMP, LOCATED APPROX. AS SHOWN.
 FIRST 2 DIGITS = LAST 2 DIGITS OF YEAR.
 NEXT 2 DIGITS = MANUFACTURING WORK WEEK.
 LAST DIGIT = DAY OF WEEK WITH SUNDAY = 1.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT (COMPONENT SIDE)

MATTE TIN	△ TUBE	1-406525-3
MATTE TIN	△ TRAY, PICK & PLACE COMPATIBLE	1-406525-2
MATTE TIN	TRAY	1-406525-1
BRIGHT TIN-LEAD	△ TUBE	406525-3
BRIGHT TIN-LEAD	△ TRAY, PICK & PLACE COMPATIBLE	406525-2
BRIGHT TIN-LEAD	TRAY	406525-1
△ TERMINAL PLATING	PACKAGING	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DIN G. GARRETT 17SEP97	CJK G. GARRETT 17SEP97	APVD M. DERSTINE 17SEP97	NAME
0 PLC ± -	1 PLC ± -	2 PLC ± 0.25[.010]	3 PLC ± 0.13[.005]	4 PLC ± -	ANGLES ± -
PRODUCT SPEC: 108-1163-4 APPLICATION SPEC: 114-2154		SIZE: A1 WEIGHT: -		CUSTOMER DRAWING	
MATERIAL: - FINISH: -		SCALE: 4:1		SHEET: 1 OF 1 REV: D2	

STE TE Connectivity
 INVERTED MODULAR JACK ASSEMBLY, 1X1